

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of manufacturing a thin film element comprising:

forming element chips including at least one of a plurality of functional elements on a first substrate through a peel layer;

adhering a second flexible substrate onto the element chips through an adhesive layer;

transferring the element chips including at least one of a plurality of functional elements formed on a first substrate onto onto the second flexible substrate peeled from the first substrate, the element chips being rectangular; and

arranging short sides of the element chips along a curving direction of the second substrate.

2. (Original) The method of manufacturing a thin film element according to Claim 1, the functional elements being thin film transistors.

3. (Original) A thin film transistor circuit substrate comprising:

thin film transistors manufactured by the method of manufacturing a thin film element according to Claim 2.

4. (Original) An active matrix display device, comprising:  
thin film transistors manufactured by the method of manufacturing a thin film element according to Claim 2, the thin film transistors being usable as active matrix elements.

5. (Original) An electro-optical device, comprising:

the thin film transistor circuit substrate according to Claim 3.

6. (Original) An electronic apparatus, comprising:  
the electro-optical device according to Claim 5.

**Amendments to the Drawings:**

The attached replacement drawing sheets makes changes to Figs. 1 and 2 and replaces the original sheets with Figs. 1 and 2.

Attachment: Replacement Sheets